REMARKS/ARGUMENTS

Examiner D. Nguyen is thanked for the thorough Search and Examination of the Subject Application for Patent.

Page 1 of the Specification has been amended, as required by the Examiner, to indicate that the present application is a division of Patent Application serial number 08/518,182, having a filing date of 08/23/95, now U.S. Pat. No. 6,365,500 B1; which is a Continuation of Patent Application serial number 08/239,375, filing date 5/6/94, now abandoned.

Page 1 of the Specification has also been amended to indicate that U.S. Pat. No. 5,393,679 should be U.S. Pat. No. 5,393,697 as required by the Examiner, thereby correcting a typographical error.

Reconsideration of the Objection to the Disclosure is requested. The Specification has been amended to correct the numbers of the related Patent Applications and the identification of the parent Patent Application as required by the Examiner.

Reconsideration of the Rejection of Claims 1-6 under U.S.C. 102(b) as being anticipated by Chang et al. (U.S. Pat. No. 5,578,527) is requested. U.S. Pat. No. 5,587,527 has a file date of June 23, 1995.

Claims 1-6 of the present application were included in Patent Application Serial No. 08/239,375 filed on May 6, 1994. A File Wrapper Continuation of Patent Application Serial No. 08/239,375 was filed on August 23, 1995 and given Application Serial No. 08/518,182 and filing date of August 23, 1995. As a result of a Restriction Requirement in an Office Action against Serial No. 08/239,375 dated October 4, 1994 Claims 1-6 were cancelled without prejudice and were filed in the present Divisional Application, Serial No. 10/061,023 on January 30, 2002. Thus the date of invention of Claims 1-6 is May 6, 1994 which predates the file date of June 23, 1995 for U.S. Pat. No. 5,587,527. It is believed that since the invention of Claims 1-6 predates the file date of U.S. Pat. No. 5,587,527; U.S. Pat. No. 5,587,527 cannot be used as a reference against Claims 1-6 of the present application. Reconsideration of the Rejection of Claims 1-6 under U.S.C. 102(b) as being anticipated by Chang et al. (U.S. Pat. No. 5,578,527), and Allowance of Claims 1-6, are requested.

With the removal of Chang et al. (U.S. Pat. No. 5,578,527) as a reference against Claims 1-6, it is presumed that Claim 6 is Allowable, since no additional rejections of Claim 6 were indicated.

Reconsideration of the Rejection of Claims 1-5 under 35 U.S.C. 103(a) as being unpatentable over Karnezos (U.S. Pat. No. 4,813,129) in view of Afzali-Ardakani et al. (U.S. Pat. No. 5,397,863) is requested. Claims 1-5 describe a bonded structure comprising the key limitations of "a composite bump comprised of a polymer body and a

conductive metal coating covering said polymer body" wherein "said polymer body has a Young's Modulus of between about 400,000 and 500,000 pounds per square inch".

The invention of Karnezos describes an interconnection structure for PC boards and integrated circuits. Karnezos describes a number of buttons for interconnections between one substrate having input/output pads and a second substrate having input/output pads. The buttons described by Karnezos have a resilient core made from an organic material, such as polyimide, and are covered with a metallic coating, see column 4, lines 15-40. Karnezos does not describe a particular Young's Modulus for the resilient core, as is specified in Claims 1-5. The limitation of the Young's Modulus of between about 400,000 and 500,000 described in Claims 1-5 insures that when the composite bump is deformed when the connection is formed, as is described in Claims 1-5, the composite bump will not later change shape and disturb the integrity of the connection. Use of a polymer having a Young's Modulus of between about 400,000 and 500,000 pounds per square inch is neither described nor suggested by Karnezos.

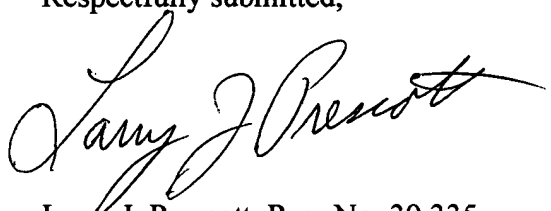
Afzali-Ardakani et al. describe improved dielectric materials suitable for use in high performance electronic device packaging and printed circuit boards, see column 1, lines 34-38. Some of the properties that Afzali-Ardakani et al. seek to modify are the thermal coefficient of expansion, dielectric constant, and conductivity of the dielectric, see column 4, lines 30-68. Although Afzali-Ardakani et al. describe the use of a polyamic acid polyimide precursor the properties of interest are thermal coefficient of expansion and dielectric constant with no discussion of the role of Young's Modulus.

Afzali-Ardakani et al. do not describe nor suggest a polymer body having a Young's Modulus of between about 400,000 and 500,000 pounds per square inch, as is described in Claims 1-5.

It is believed that the bonded structure of Claims 1-5 wherein the polymer body of the composite bump has a Young's Modulus of between about 400,000 and 500,000 pounds per square inch is different from and not obvious from Karnezos. It is also believed that the polymers and polymer properties described by Afzali-Ardakani et al. do not make a polymer body for a composite bump having a Young's Modulus of between about 400,000 and 500,000 pounds per square inch, as described in Claims 1-5 an obvious extension of Karnezos. Reconsideration of the Rejection of Claims 1-5 under 35 U.S.C. 103(a) as being unpatentable over Karnezos in view of Afzali-Ardakani et al., and allowance of Claims 1-5, are requested.

It is requested that should Examiner Nguyen not find that the Claims are now Allowable that the Examiner call the undersigned Agent at (845)-462-5363 to overcome any problems preventing allowance.

Respectfully submitted,



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